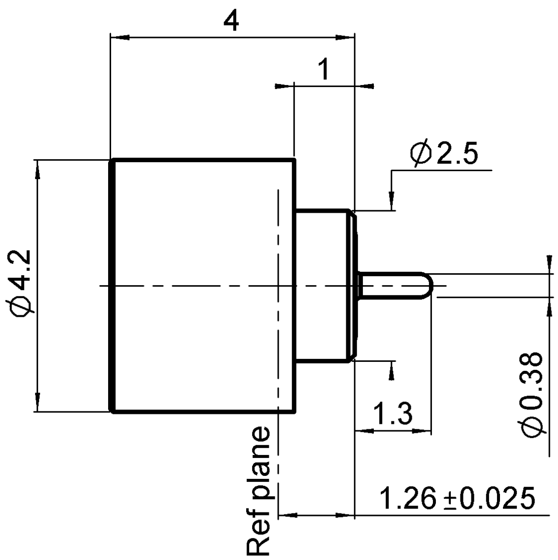
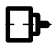
HERMETIC STRAIGHT MALE RECEPTACLE

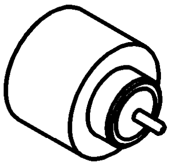
SOLDER TYPE - SMOOTH BORE

R222.645.730

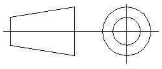
Series : **SMP**




Scale: 1/1



All dimensions are in mm.



COMPONENTS	MATERIALS	PLATINGS (µm)
BODY	**DILVER P1**	**GOLD 0.5 OVER NICKEL 2**
CENTER CONTACT	**DILVER P1**	**GOLD 0.5 OVER NICKEL 2**
OUTER CONTACT	-	-
INSULATOR	**GLASS**	
GASKET	-	
OTHERS PARTS	-	-
-	-	-
-	-	-

Issue : 0950 B

In the effort to improve our products, we reserve the right to make changes judged to be necessary.

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PACKAGING

Standard	Unit	Other
100	**'W' option**	**Contact us**

ELECTRICAL CHARACTERISTICS

Impedance	**50**	Ω
Frequency	**0-18**	GHz
VSWR	**1.15** + **0,0000**	x F(GHz) Maxi
Insertion loss	**0.12**	√F(GHz) dB Maxi
RF leakage	- (	- F(GHz)) dB Maxi
Voltage rating	**335**	Veff Maxi
Dielectric withstanding voltage	**500**	Veff mini
Insulation resistance	**5000**	MΩ mini

MECHANICAL CHARACTERISTICS

Center contact retention		
Axial force – Mating end	**6.8**	N mini
Axial force – Opposite end	**6.8**	N mini
Torque		N.cm mini

Recommended torque		
Mating		N.cm
Panel nut		N.cm

Mating life	**1000**	Cycles mini
Weight	**0,1500**	g

SPECIFICATION

ENVIRONMENTAL

Operating temperature	**-65/+165**	° C
Hermetic seal	**10-8**	Atm.cm3/s
Panel leakage		

OTHERS CHARACTERISTICS

Assembly instruction

Others :

RADIALL®

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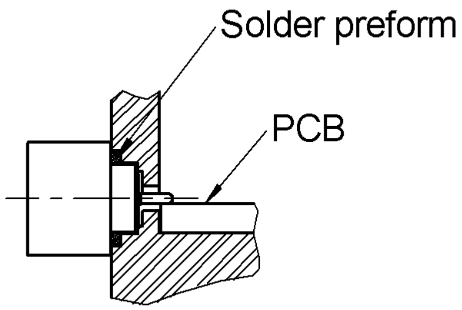
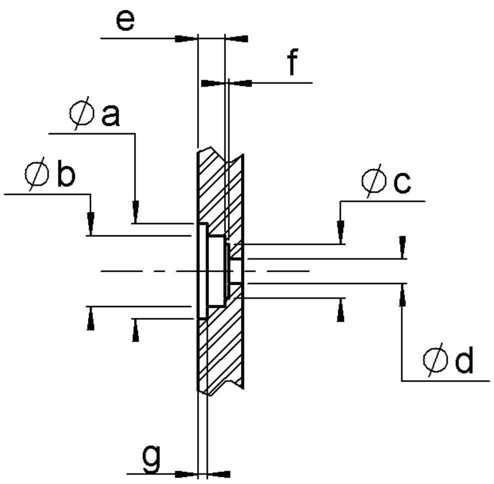


1. Degrease and clean connector and box
2. Solder the connector on the panel
   we advise SnAg4 Cu0.5, we recommand a low residue flux.
   Preheating at 100 °C. Take care not to exceed 260°C during solder operation
3. Solder the pin on the track
   we advise SnAg4 Cu0.5, we recommand a low residue flux.
   Preheating at 100 °C (only for ceramic substrate). Take care not to exceed 260°C during solder operation

Panel mounting hole



a	3,43 - 3,47
b	2,59 - 2,61
c	1,95 - 2,05
d	0,87 - 0,91
e	0,94 - 0,99
f	0,13 - 0,17
g	0,28 - 0,38